508403258 02/23/2024

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 Assignment ID: PATI47936

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date	
Yong-sik WON	06/17/2011	
Sang-uk LEE	06/17/2011	

# **RECEIVING PARTY DATA**

Company Name:	me: Magnachip Semiconductor, Ltd.	
Street Address:	eet Address: 1, Hyangjeong-dong, Hungduk-gu, Chungbuk	
City:	Cheongju-si	
State/Country:	KOREA, REPUBLIC OF	

# **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14753868

# **CORRESPONDENCE DATA**

**Fax Number:** 2023153758

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202)429-0020 Email: pto@nsiplaw.com

Correspondent Name: NSIP Law Address Line 1: P.O. Box 65745

Address Line 4: Washington, DISTRICT OF COLUMBIA 20035

ATTORNEY DOCKET NUMBER:	023103.0047D1
NAME OF SUBMITTER:	Isabelle Osborne
SIGNATURE:	Isabelle Osborne
DATE SIGNED:	02/23/2024

### **Total Attachments: 2**

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PATENT 508403258 REEL: 066543 FRAME: 0492

### **ASSIGNMENT**

For valuable consideration, we,

Yong-sik WON 1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk,

Republic of Korea

Sang-uk LEE 1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk,

Republic of Korea

hereby assign to:

### MAGNACHIP SEMICONDUCTOR, LTD., a Republic of Korea

corporation/institute/institution having principal executive office(s) or place of business

at: 1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea; and

its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of U.S. Patent Application Number 13/193,679 \_\_ filed \_\_**July 29, 2011** at the U.S. Patent & Trademark Office signed by us, with title SEMICONDUCTOR DEVICE AND METHOD OF **FABRICATING THE SAME**, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and application serial number of said application when known; this Assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, preliminary statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

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	IN TESTIMO	ONY/WITNE	ESS WHEREOF,	, we, und	ersigned ir	nventors (A	Assignors)	intending
to b	e legally bound,	have hereto	affixed our sig	natures.				

This 17 day of 06, 2011

Signature: Yong-sik WON

This 17 day of 06, 2011

Signature: Sang-uk LEE

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**RECORDED: 02/23/2024** 

PATENT REEL: 066543 FRAME: 0494